

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-4. (Canceled)

5. (Currently Amended) ~~A method according to claim 4~~ A deposition method capable of filling recesses in a substrate, the method comprising:

(a) providing a substrate having recesses defining side walls and recess bottoms;

(b) exposing the substrate to an energized deposition gas comprising a first component comprising ozone and a second component, to deposit a first layer of a material in the recess at different rates over the side walls and recess bottoms; and

(c) reducing the ratio of the first component to the second component, to deposit a second layer of the material over the first layer in the recess;

wherein the ratio-reducing step is performed by reducing the flow rate of O<sub>3</sub>, and  
wherein the ratio-reducing step is performed for about 30 seconds.

6. (Currently Amended) A method according to claim [[1]] 5 wherein the second component comprises TEOS.

7.-9. (Canceled).

10. (Currently Amended) ~~A method according to claim 1 comprising providing a substrate~~ A deposition method capable of filling recesses in a substrate, the method comprising:

(a) providing a substrate having recesses defining side walls and recess bottoms, the substrate having recesses between polysilicon gates;

(b) exposing the substrate to an energized deposition gas comprising a first component comprising ozone and a second component, to deposit a first layer of a material in the recess at different rates over the side walls and recess bottoms; and

(c) reducing the ratio of the first component to the second component, to deposit a second layer of the material over the first layer in the recess.

11. (Original) A method according to claim 10 wherein the recesses have sidewall portions covered with silicon nitride spacers, and wherein the silicon nitride spacers, the polysilicon gates and the other portions of the substrate, are covered with a silicon nitride liner.

12. (Currently Amended) ~~A method according to claim 1~~ A deposition method capable of filling recesses in a substrate, the method comprising:

(a) providing a substrate having recesses defining side walls and recess bottoms;

(b) exposing the substrate to an energized deposition gas comprising a first component comprising ozone and a second component, to deposit a first layer of a material in the recess at different rates over the side walls and recess bottoms, wherein the first layer has a thickness of from about 200 to about 800 angstroms; and

(c) reducing the ratio of the first component to the second component, to deposit a second layer of the material over the first layer in the recess.

13-14. (Canceled)

15. (Currently Amended) ~~A method according to claim 13~~ A deposition method capable of filling recesses in a substrate, the method comprising:

(a) providing a substrate having recesses defining side walls and recess bottoms;

(b) exposing the substrate to an energized deposition gas comprising a first volumetric flow ratio of O<sub>2</sub> and TEOS, to deposit a first layer of silicon oxide in the recess at different rates over the side walls and recess bottoms; and

(c) reducing the volumetric flow ratio of the  $O_3$  to the TEOS, to deposit a second layer of silicon oxide over the first layer in the recess, wherein the ratio-reducing step is performed for about 30 seconds.

16. (Currently Amended) ~~A method according to claim 13~~ A deposition method capable of filling recesses in a substrate, the method comprising:

(a) providing a substrate having recesses defining side walls and recess bottoms, wherein the recesses are between polysilicon gates and have sidewall portions covered with silicon nitride spacers, and wherein the silicon nitride spacers, the polysilicon gates and the other portions of the substrate, are covered with a silicon nitride liner;

(b) exposing the substrate to an energized deposition gas comprising a first volumetric flow ratio of  $O_3$  and TEOS, to deposit a first layer of silicon oxide in the recess at different rates over the side walls and recess bottoms; and

(c) reducing the volumetric flow ratio of the  $O_3$  to the TEOS, to deposit a second layer of silicon oxide over the first layer in the recess.

17. (Original) A method according to claim 16 wherein the silicon nitride liner comprises reentrant cavities, and wherein the reentrant cavities are smoothed by the first layer.

18. (Canceled)

19. (Currently Amended) A method according to claim ~~[[18]]~~ 17 comprising depositing the first layer to a thickness of from about 200 to about 800 angstroms.

20. (Previously Presented) A deposition method capable of filling recesses on a substrate, the recesses being between polysilicon gates and having sidewall portions covered with silicon nitride spacers, and wherein the silicon nitride spacers, the polysilicon gates and the other portions of the substrate, are covered with a silicon nitride liner, the method comprising:

(a) providing an energized deposition gas comprising  $O_3$  and TEOS, to form a first layer of silicon oxide in the recess at different rates over side walls and recess bottoms of the recess; and

(b) reducing the volumetric flow ratio of  $O_3$  to TEOS in the deposition gas, to fill the recesses with silicon oxide after the first layer is formed.

21. (Original) A method according to claim 20 wherein the ratio-reducing step is performed by reducing the flow rate of  $O_3$ .

22. (Original) A method according to claim 20 wherein the ratio-reducing step is performed for about 30 seconds.

23. (Original) A method according to claim 20 comprising depositing the first layer to a thickness of from about 200 to about 800 angstroms.

24. (Canceled)

25. (Currently Amended) A method of filling recesses with a dielectric material, the method comprising:

disposing a substrate defining a recess into a processing chamber; and  
continuously introducing a deposition gas into a processing chamber while  
gradually changing a relative composition of the deposition gas, such that conformality of the  
dielectric material within the recess decreases, and deposition rate of the dielectric material  
within the recess increases, The method of claim 24 wherein the deposition gas comprises of  
ozone and tetraethoxysilane (TEOS), and a ratio of ozone:TEOS is decreased over time.

26. (Previously Presented) The method of claim 25 wherein the ozone:TEOS ratio is decreased by reducing a rate of ozone flowed into the processing chamber.

27. (Previously Presented) The method of claim 25 wherein the ozone:TEOS ratio is decreased by increasing a rate of TEOS flowed into the processing chamber.

28. (Previously Presented) The method of claim 25 wherein the ozone:TEOS ratio is changed over a period of about 30 seconds or more.

29. (Currently Amended) The method of claim ~~[[24]]~~ 25 wherein the substrate defines the recess as a shallow trench.

30. (Currently Amended) The method of claim ~~[[24]]~~ 25 wherein the substrate defines the recess between raised features.

31. (Previously Presented) The method of claim 30 wherein the raised features comprise adjacent gate structures.

32. (Currently Amended) The method of claim ~~[[24]]~~ 25 wherein the dielectric material is formed over silicon nitride lining the recess.